DETAILED ACTION

REASONS FOR ALLOWANCE

Claims 2, 4-12 and 24 are allowed.

The following is an examiner's statement of reasons for allowance:

The prior art of record fails to disclose the combination of an overmolded electrical component recited in the base claims 4 and 24, including the combination of the structure comprising: the polymeric overmolding being composed of a polymeric composite including a synthetic resin matrix and inorganic filler particles substantially uniformly distributed in the synthetic resin matrix, the inorganic filler particles having a platelet structure defined by opposite substantially flat and substantially parallel faces and being characterized by a dimensions between about 1 and 700 nanometers, the inorganic filler particle content being 20 percent or less by weight based on the weight of the polymeric composite (claim 4); and the polymeric composite includes a synthetic resin matrix and inorganic filler particles substantially uniformly distributed in the synthetic resin matrix, the inorganic filler particles having a platelet structure defined by opposite substantially flat and substantially parallel faces and being characterized by a thickness between about 1 and 20 nanometers and a ratio of a surface area of a face to the thickness of at least 100, the inorganic filler particle content being 20% or less by weight based on the weight of the polymer composite (claim 24).

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to DiLinh Nguyen whose telephone number is (571) 272-1712. The examiner can normally be reached on 8:00AM - 5:00PM (M-F).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Hoai v Pham/ Primary Examiner, Art Unit 2814